



Final Product Change Notification

201308003F01

Issue Date: 14-Aug-2013
Effective Date: 11-Nov-2013

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QUALITY

Management Summary

Introduction of a changed packing method for all MOxx module deliveries on reels in order to save waste and storage volume.

Change Category

Wafer Fab process	Assembly Process	Product Marking	Design
Wafer Fab materials	Assembly Materials	Electrical spec./Test coverage	Mechanical Specification
Wafer Fab location	Assembly Location	Test Location	Packing/Shipping/Labeling

New Packing Method for MOxx Contactless Modules

Details of this Change

A new single box packing method for all MOxx module deliveries on reels will be introduced to replace the existing double box packing method. At least the same protection level for the product as given by the existing packing method is maintained.

Why do we Implement this Change

The new packing methods reduces waste and decreases storage volume requirements per reel, while maintaining at least the same protection level.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 10-Nov-2013

Impact

no impact to the product's functionality anticipated.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 13-Sep-2013.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Adolf Hansemann
Position Product Quality Engineer
e-mail address adolf.hansemann@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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